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Suwon-si (KR)(21) Appl. No.: **18/081,079**(22) Filed: **Dec. 14, 2022**(57) **ABSTRACT**

A multilayer electronic component includes a body including a dielectric layer and internal electrodes stacked in a first direction with the dielectric layer interposed therebetween and external electrodes including a first electrode layer connected to the internal electrodes and including Ni, and a second electrode layer disposed on the first electrode layer and including an Ni—Cu alloy. A Cu content of the second electrode layer is 70 mol to 90 mol compared to 100 mol of the total content of Ni and Cu of the second electrode layer.

